

Program funded by the Professional Services Development Assistance Scheme (PSDAS)

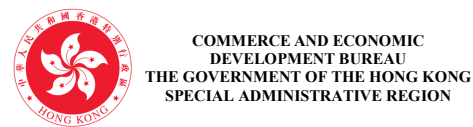
**Organizer**



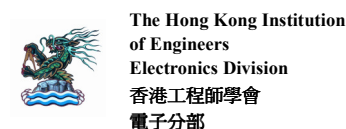
**Implementation Organization**



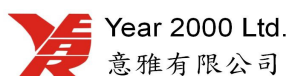
**Funding Organization**



**Collaborating Organization**



**Supporting Organization**



**Seminar on PCB and Packaging Technologies**

**Date** 20 February 2009 (Friday)  
**Time** 9:30 ~ 17:30  
**Venue** Function Room, 1/F., HKPC Building, 78 Tat Chee Avenue, Kowloon  
**Language** English  
**Fee** HK\$100 per person <sup>Note 1, 2, 3, 4</sup>

**Note:**

1. Reimbursement for 75% course fees from HKSTP Technical Assistance Fund applicable for HKSTP member companies.
2. The seminar is designed to satisfy the HKIE CPD requirements for one full CPD day.
3. The seminar is also designed to satisfy the ISMHK CEH requirements for 7 CEHs.
4. The registration fee includes presentation's handout and refreshments for coffee break.

**Introduction**

In order to enhance knowledge of engineers in the electronics industry on emerging technology discoveries and exploit these technologies in the development of new materials, components, and products, Physical Society of Hong Kong has successfully applied funding support from Professional Services Development Assistance Scheme of Commerce and Economic Development Bureau to establish a project titled "Enhance the Capability of Engineers in the Electronics Industry in Exploiting New Technologies to Develop New Materials, Components and Products". The project will deliver two seminars and one international symposium. *Seminar on PCB and Packaging Technologies* is the second seminar of this project.

**Seminar Rundown**

9:00-9:30	Registration	
9:30-9:35	Welcome Message	Professor Kam-Sing WONG President, Physical Society of Hong Kong
9:35-9:45	Keynote Speech – PCB Market and Technology Trend	Mr. Daniel CHAN Global PCB Council Chairman, IBM Hong Kong Limited
	Topic	Speaker
9:45-10:15	Electronic Packaging of High Power Light Emitting Diodes	Professor Philip CHAN Dean of Engineering, Director of Center for Advanced Microsystems Packaging, HK University of Science And Technology
10:15-10:45	Flip Chip and Wafer-Level Chip Scale Packaging: Market Updates, Key Processes and Application Examples	Dr. Ivan SHAM, Manager, HK Applied Science & Technology Research Institute Co. Ltd. (ASTRI)
10:45-11:00	Coffee Break	

Topic		Speaker
11:00–11:30	3D Integration – A Solution for Next Generation Silicon Devices	Dr. Daniel SHI, Director, HK Applied Science & Technology Research Institute Co. Ltd. (ASTRI)
11:30–12:00	Embedded Substrate Matter (EPADs)	Mr. Onishi Tetsuya Consultant, Grand Joint Technology Ltd.
12:00–12:30	Advanced IC Package/SiP and PCB Co-Design solution	Mr. Wu JUN Senior Application Engineer, Cadence Design Systems, Inc.
12:30–14:00	Lunch Break	
14:00–14:45	Green PCB and Substrate for sustainability	Professor Winco YUNG, Associate Professor, Department of Industrial and Systems Engineering, HK Polytechnic University
14:45–15:15	HDI PCB application of Mobile device: Trend and opportunity	Miss Tarja Rapala CTO, Meadville Group
15:15–15:45	The latest change momentum of computer server PCB and packaging technology	Mr. Daniel CHAN Global PCB Council Chairman, IBM Hong Kong Limited
15:45–16:00	Coffee Break	
16:00–16:30	PCB Design Team Collaboration – Enabling Design with Distributed, Multi-disciplined Teams	Dr. Lifu YOU China Technical Marketing Manager, System Design Division (SDD), Mentor Graphics
16:30–17:00	Welding technology used in repair both bare PCB and PCB with components	Mr. PC. LEUNG Director, Year 2000 Ltd
17:00–17:30	a) PCB Reliability, EMC, PCB assembly b) Plant Tour for HKPC Reliability and EMC Labs	Mr. Raymond CHIU Principal Consultant, Automotive and Electronics Division, Hong Kong Productivity Council
End of Seminar		

**Application:** Please complete the enrolment form and send to 2788 5405 by fax for registration, then send the completed form together with the registration fee [*i.e.* All cheques should be crossed and made payable to **“Physical Society of Hong Kong”**. Please also write down participant’s name and course name at the back of the cheque] to **HKPC, AED, 3/F, HKPC Building, 78, Tat Chee Avenue, Kowloon** on or before 17 February 2009.

**Enquiry:** Please call 2788 5775 (Miss Grace Chau) or 2788 5756 (Miss Jennie Kwok) or fax 2788 5405 or Email: [grace@hkpc.org](mailto:grace@hkpc.org) or [jennie@hkpc.org](mailto:jennie@hkpc.org) (Website: [www.hkpc.org](http://www.hkpc.org))

## Enrolment Form

1. Course Name: Seminar on PCB and Packaging Technologies (40087393)  
Date: 20 February 2009  
Fee: HK\$100.- per person

2. Mr/Ms/Mrs \_\_\_\_\_  
Position \_\_\_\_\_ Email \_\_\_\_\_

3. Organization \_\_\_\_\_  
Business Address \_\_\_\_\_  
Tel \_\_\_\_\_ Fax \_\_\_\_\_

Signature \_\_\_\_\_ Date \_\_\_\_\_

**IMPORTANT:**

- Course fee must accompany this form (or its photocopy), otherwise enrolment may be rejected.
- All payment should made by cheques. Cheques are subject to bank clearance.
- Enrolment fee is not refundable unless HKPC is notified in writing of your withdrawal at least 10 working days before the course commences. A handling charge of HK\$200 will also be levied.
- An applicant may, subject on approval from HKPC, nominate a substitute to attend the course on his/her behalf.
- The information provided will be used for the process of enrolment application, statistical purposes and other related matters. It may be provided to persons authorized to process the information for purpose relating to course enrolment.
- Organizer reserves the right to amend program without prior notice.

Disclaimer: Any opinions, findings, conclusions or recommendations expressed in this material / any event organized under this Project do not reflect the views of the Government of the Hong Kong Special Administrative Region or the Vetting Committee for the Professional Services Development Assistance Scheme.

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發送者：香港生產力促進局 香港九龍達之路 78 號生產力大樓 電話：(852) 2788-5775.  
If you do not wish to receive further information from HKPC, please inform us via fax at (852) 3187-4531.  
若閣下不欲再接收本局信息，請以傳真：(852) 3187-4531 通知我們。